

	Type	L #	Hits	Search Text	DBs
1	IS&R	L1	5634	(257/751-753,758,762,767,773,774).CCLS.	USPAT
2	IS&R	L2	2423	(438/627,643,653,687,927).CCLS.	USPAT
3	BRS	L3	193	((copper near2 sulfide) or CuS or Cu\$1S) and (((438/618,622,624,626-628,631,634,637,639,643-645,653,654,666,672,687,927) or (257/751-753,758,762,767,773,774)).CCLS.)	USPAT
4	BRS	L4	78	((copper near2 sulfide) or CuS or Cu\$1S) and (((438/618,622,624,626-628,631,634,637,639,643-645,653,654,666,672,687,927) or (257/751-753,758,762,767,773,774)).CCLS.)	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB
5	BRS	L5	2	("6683002").URPN.	USPAT
6	IS&R	L6	3715	(257/751-753,758,762,767,773,774).CCLS.	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB
7	IS&R	L7	1275	(438/627,643,653,687,927).CCLS.	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB
8	BRS	L8	494	((copper with sulfide) or (Cu with S) or CuS) and (interconnect interconnection)	USPAT
9	BRS	L9	1528	((copper with sulfide) or (Cu with S) or CuS) and (interconnect interconnection)	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB
10	BRS	L10	321	((copper with sulfide) or (Cu with S) or CuS) and (interconnect interconnection) and (substrate semiconductor)	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB
11	BRS	L11	238	((copper with sulfide) or (Cu with S) or CuS) and (interconnect interconnection) and (substrate semiconductor) and (dielectric insulation insulating)	US-PGPUB; USOCR; EPO; JPO; DERWENT; IBM_TDB

	Time Stamp	Comments	Error Definition	Errors
1	2005/07/22 07:32			
2	2005/07/22 07:35			
3	2005/07/22 08:16			
4	2005/07/22 08:17			
5	2005/07/22 08:51			
6	2005/07/22 09:03			
7	2005/07/22 09:04			
8	2005/07/22 11:14			
9	2005/07/22 11:14			
10	2005/07/22 11:15			
11	2005/07/22 11:15			

	Type	L #	Hits	Search Text	DBs
12	BRS	L24	1	(interface and (copper Cu) and (sulfide S) and (passivation etch adj stop) and (interconnect interconnection)).CLM.	USPAT
13	BRS	L25	7	((interface lining liner barrier diffusion) and (copper Cu) and (sulfide S) and (passivation etch adj stop) and (interconnect interconnection)).CLM.	USPAT
14	BRS	L26	12	((interface lining liner barrier diffusion) and (copper Cu) and (sulfide S) and (passivation etch adj stop) and (interconnect interconnection)).CLM.	US-PGPUB

	Time Stamp	Comments	Error Definition	Errors
12	2005/07/22 12:16			
13	2005/07/22 12:21			
14	2005/07/22 12:21			